



Material Content Data Sheet



Sales Product Name		BTN8982TA		Issued		19. July 2018		
MA#		MA001079222						
Package		PG-TO263-7-1		Weight*		1535.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.214	0.47	0.47	4699	4699
leadframe	non noble metal	iron	7439-89-6	0.810	0.05		527	
	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	copper	7440-50-8	808.613	52.67	52.74	526768	527453
wire	non noble metal	aluminium	7429-90-5	14.233	0.93	0.93	9272	9272
encapsulation	organic material	carbon black	1333-86-4	8.684	0.57		5657	
	plastics	epoxy resin	-	95.519	6.22		62225	
	inorganic material	silicondioxide	60676-86-0	474.702	30.92	37.71	309242	377124
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8493	8493
plating	non noble metal	nickel	7440-02-0	0.212	0.01		138	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	526767	138
glue	plastics	Polyimide	26023-21-2	0.179	0.01	0.01	117	117
solder	noble metal	silver	7440-22-4	0.131	0.01		86	
	non noble metal	tin	7440-31-5	0.105	0.01		68	
	non noble metal	lead	7439-92-1	5.019	0.33	0.35	3270	3424
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.92	6.93	69190	69280
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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